

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|--|------------------|---------|------------------|
| L1 | 208 | 360/319.ccls. | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:16 |
| L2 | 9 | ("20020034055" "20020075609" "5739987" "5894384" "6078484" "6223420" "6317301" "6765768" "6785099").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/29 15:28 |
| L3 | 2 | "5855711".pn. | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:28 |
| L4 | 24 | ("5085720" "5130067" "5254191" "5370759" "5387474" "5456778" "5470412" "5474741").PN. OR ("5855711").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/29 15:35 |
| L5 | 57 | pcb and plug and laminating | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:40 |
| L6 | 1 | "20030110629".pn. | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:41 |
| L7 | 0 | HORNG near Gwo.inv. | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:41 |
| L8 | 2 | HORNG near Gwo.inv. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:41 |
| L9 | 0 | ("2004/0045656").URPN. | USPAT | OR | ON | 2006/08/29 15:43 |
| L10 | 522 | chip near package near substrate | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:45 |
| L11 | 0 | chip near package near substrate and filling and firing and stacking and planariz\$3 | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:46 |

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| L12 | 0 | chip near package near substrate and filling and stacking and planariz\$3 | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:46 |
| L13 | 0 | chip near package near substrate and filling and stacking and planariz\$3 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:46 |
| L14 | 25 | chip near package near substrate and planariz\$3 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:47 |
| L15 | 13 | chip near package near substrate same method and "29"/\$.ccls. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:48 |
| L16 | 140 | chip near package near substrate same method and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:53 |
| L17 | 11 | chip near package near substrate same method and "257"/\$.ccls. and "29"/\$.ccls. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:54 |
| L18 | 8 | chip near package near substrate same method and "438"/\$.ccls. and "29"/\$.ccls. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:55 |

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| L19 | 0 | chip near package near substrate same method and "156"/\$.ccls. and "29"/\$.ccls. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/29 15:55 |
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